



Peter Stampka

Date of Birth: November 29, 1959
Place of Birth: Regensburg, Germany
Education: Study of Mechanical Engineering
Polytechnical Institute of Albstadt-Ebingen

Business Experience:

1994 – 1997	Siemens AG, Regensburg	Development Engineer Chip Card Packages, Assembly Technology unit Semiconductor Group
1997 – 1998	Siemens AG, Regensburg	Senior Manager Packaging Definition, Assembly Technology unit Semiconductor Group
1998 – 1999	Siemens AG, Regensburg	Senior Manager Technical Marketing, Chip Card business unit Semiconductor Group
1999 – 2004	Infineon Technologies AG, Regensburg	Marketing Director Security Packaging Center, Security business unit, Secure Mobile Solutions business group
Since January 2005	Infineon Technologies AG, Regensburg	Marketing Director Security Packaging Center, Security business unit, Automotive, Industrial & Multi-Market business group